

Table 3.8 Low-side MOSFET Gate Drivers^a

Part #	Mfg ^d	# channels	Speed ^b						logic thresh ^p	source below gnd? current limit	UVLO? enable?	inv?	non-inv?	output rail-to-rail?	Packages			Comments	
			V _{min} (V)	V _{max} (V)	I _{pk} (A)	t _d + 0.5t _r (ns, typ)	C _{load} (nF)								TO220, Dpak	DIP	SOIC, MSOP	SOT23	
TC4426-28	MC+	2	4.5	18	1.5	55	1	T	-	-	-	n	n	•	-	•	•	-	G,H
TC4423-25	MC+	2	4.5	18	3	70	1.8	T	-	-	-	n	n	•	-	•	•	-	G,H
TC4420,29	MC+	2	4.5	18	6	80	2.5	T	-	-	-	•	•	•	-	•	•	-	G
TC4421-22	MC+	1	4.5	18	9	85	10	T	-	-	-	•	•	•	-	•	•	-	G,J
FAN3111	F	1	4.5	18	1	20	0.5	C	-	-	c	c	c	•	-	-	-	-	-
FAN3100C,T	F	1	4.5	18	2	20	1	C,T	-	-	•	c	c	c	•	-	-	-	•
FAN3180	F	1	5	18	2	30	1	T	-	-	•	-	•	•	-	-	-	-	B
FAN3216-17	F	2	4.5	18	2	25	2.2	T	-	-	•	-	•	•	-	-	-	-	D
FAN3226-29C,T	F	2	4.5	18	2	25	1	C,T	-	-	•	c	c	c	•	-	-	-	C,E
FAN3213-14	F	2	4.5	18	4	20	2.2	T	-	-	•	-	•	•	-	-	-	-	C
FAN3223-25C,T	F	2	4.5	18	4	25	2.2	C,T	-	-	•	c	c	c	•	-	-	-	E
FAN3121-22	F	1	4.5	18	9	21	10	T	-	-	•	•	•	•	-	-	-	-	-
IRS44273L	IR	1	12	20	1.5	50	1	T	-	-	•	-	•	-	-	-	-	-	-
IR25600	IR	2	6	20	1.5	75	1	T	-	-	-	-	•	-	-	•	•	-	-
MAX17600-05	MA	2	4	14	4	15	1	C5,T	-	-	•	n	n	•	-	-	•	-	H
MAX5054-07	MA	2	4	15	4	38	5	C,T	-	-	-	c	c	c	•	-	-	•	-
MAX5048A,B	MA	1	4	12.6	7.6 ^h	18	1	C,T	-	-	•	c	c	c	•	-	-	-	-
UCC37323-25 ^k	TI	2	4.5	15	4	47	1.8	T	-	-	-	•	•	•	-	-	•	•	-
UCC27517	TI	1	4.7	20	4	17	1.8	T	-	-	•	c	c	c	-	-	-	-	-
UCC27516-19	TI	1	4.7	20	4	17,21	1.8	T,C	-	-	•	•	•	•	-	-	-	-	-
UCC27523-26	TI	2	4.7	20	5	17	1.8	T	-	-	•	•	•	•	-	-	•	•	E,H
UCC37321-22 ^k	TI	1	4	15	9	50	10	T	-	-	-	•	•	•	-	-	•	•	-
MIC44F18-20	MI	1	4.5	13.2	6	24	1	T	-	-	•	•	•	•	-	-	•	-	-
ADP3623-25	A	2	4.5	18	4	28	2.2	T	-	-	•	-	•	•	-	-	•	-	H,P
LM5110	TI	2	3.5	14	5 ^f	38	2	T	•	-	•	-	n	n	•	-	•	-	H,L
LM5112	TI	2	3.5	14	79	38	2	T	•	-	•	-	n	n	-	-	•	-	H,L,M
LM5114	TI	1	4	12.6	7.6 ^h	16	1	C	-	-	•	c	c	c	•	-	-	•	-
ISL89367	IN	2	4.5	16	6	45	10	F	•	-	•	n	o	o	•	-	•	-	N
ISL89160-62	IN	2	4.5	16	6	45	10	C5,T	-	-	•	-	•	•	-	-	•	-	O
MC34151	O	2	6.5	18	1.5	50	1	T	-	-	•	-	•	-	-	-	•	-	-
IR2121	IR	1	12	18	2 ^e	200	3.3	T	-	•	-	-	•	-	-	•	-	-	F
UC3708	TI	2	5	35	3	37	1	T	-	-	-	•	-	•	-	-	•	-	-
IXDD602	IX	1	4.5	35	2	50	1	C5	-	-	•	•	•	•	-	•	•	-	H,R
IXDD604	IX	1	4.5	35	4	40	1	C5	-	-	•	•	•	•	-	•	•	-	H,R
IXDD609	IX	1	4.5	35	9	60	10	C5	-	-	•	•	•	•	-	•	•	-	R
IXDD614	IX	1	4.5	35	14	70	15	C5	-	-	•	•	•	•	-	•	•	-	R
IXDD630	IX	1	10	35	30	65	5.6	C5	-	-	•	•	•	•	-	-	-	-	K,R
ZXGD3002-04	D	1	-	20,40	9.5	11	1	-	-	-	-	-	-	-	-	-	•	-	M,S

Notes: (a) sorted by family, within family sorted by lout; except for ZXGD3000-series, all devices swing rail-to-rail, or nearly so. (b) into Cload at V_S=12V. (c) input gate with inv and non-inv inputs. (d) A=Analog Devices; D=Diodes, Inc; F=Fairchild; IN=Intersil; IR=International Rectifier; IX=Ixys/Clare; L=LTC; MA=Maxim; MC=Microchip; MI=Micrel; O=On Semiconductor; S=STMicroelectronics; TI=Texas Instruments. (e) 1A source, 2A sink. (f) 3A source, 5A sink. (g) 3A source, 7A sink. (h) 1.3A source, 7.6A sink. (k) 37xxx for 0 to 70°C, 27xxx for -40°C to 105°C. (n) see part-specific comments. (o) XOR input sets optional invert. (p) C=CMOS; C5=5V CMOS; F=flexible, set by V_{ref-} and V_{ref+} input pins; T=TTL.

Comments: (A) suffix specifies logic threshold. (B) includes 3.3V LDO output. (C) 2ns td channel match. (D) 1ns td channel match. (E) dual inv+en, dual non-inv+en, dual inputs. (F) source-resistor current-sense input terminal, suitable for driving an IGBT. (G) industry std, many mfgs. (H) dual inv, dual non-inv, or one each. (J) for 8-pin pkgs, n- and p-ch drains on separate pins. (K) t_r, t_f = 50ns into 68nF. (L) output swing to neg rail, can be 5V below logic gnd. (M) n- and p-ch drains on separate pins. (N) resistor-programmed edge-delay timers; 2-input AND signal inputs. (O) ISL89163-65 same, but include enable inputs; ISL89166-68 same, but include resistor-programmed edge-delay timer inputs. (P) overtemp protection and output. (R) full p/n is IXDx6..., where x = N, I, D and F for non-inv, inv, dual non-inv+en, or one of each. (S) series is one each high-current high-gain npn and pnp transistor emitter-followers for pullup and down.

Review of Chapter 3

An A-to-Z summary of what we have learned in Chapter 3. This summary reviews basic principles and facts in Chapter 3, but it does not cover application circuit diagrams and practical engineering advice presented there.

¶A. FETs.

In Chapter 3 we explored the world of Field-Effect Transistors, or FETs. FETs have a conducting channel with terminals named *Drain* and *Source*. Conduction in the channel is controlled by an electric field created by a third *Gate* electrode (§3.1). As with bipolar transistors (BJTs), FETs are transconductance devices (see ¶G below), which means the drain *current* (assuming sufficient drain-to-source voltage) is controlled by the gate *voltage*.

¶B. *n*-channel and *p*-channel.

Like BJTs with their *npn* and *pnp* types, FETs come in both *n*- and *p*-channel polarities (§3.1.2). In either case the channel conductance increases if the gate voltage is taken toward the drain voltage. For example, for an *n*-channel FET with a positive drain voltage, the channel can be turned on with a sufficient positive-going voltage, and cutoff with a sufficient negative-going voltage. That's not to say the *n*-channel device requires positive and negative voltages to turn on and off. A threshold voltage V_{th} can be defined where the FET is just slightly turned on, and the channel responds to gate voltages above and below V_{th} for control.

¶C. Enhancement and Depletion Modes.

See Figure 3.8. Enhancement-mode devices have a high enough threshold voltage V_{th} that they are nonconducting (i.e., off) when their gate voltage is at $V_{GS}=0$ V. To bring such a FET into conduction, the gate of is brought positive (if *n*-channel) or negative (if *p*-channel). Depletion-mode devices, by contrast, have their threshold voltage well into the “off” direction, thus they are conducting (i.e., on) with their gate-voltage at $V_{GS}=0$ V. Thus for example you must apply a considerable negative gate voltage V_{GS} to turn off an *n*-channel depletion-mode FET. See Figure 3.9 where drain current versus gate voltage is shown for a selection of *n*-channel devices. FETs can be fabricated with the transfer curve shifted left or right (more about this in ¶H below). Figures 3.10 and 3.11 show convenient maps of the FET types.

¶D. MOSFETs and JFETs.

In metal-oxide FETs (MOSFETs) the gate electrode is fully insulated from the channel, and can be taken positive or

negative, typically up to ± 20 V. In junction FETs (JFETs) the semiconductor gate contacts the channel and acts as a diode junction, so it is insulated only in the reverse direction. Therefore JFETs are necessarily depletion mode devices; one cannot make an enhancement-mode JFET. Figures 3.6 and 3.7 show FET symbols.

¶E. FET Characteristics, Gate and Drain.

See Figure 3.13. A FET’s channel conductance and current is controlled primarily by its gate voltage, but it’s also affected by the drain voltage V_{DS} . At very low drain voltages the channel acts like a resistor, whose value is controlled by the gate (§3.1.2 and §3.2.7); this is called the *linear* region. At higher drain voltages the drain current levels off, being controlled by the gate voltage and only weakly dependent upon drain voltage; this is called the *saturated* region. In the saturated region the FET drain acts like a current source (or sink), and the device is characterized by its transconductance g_m (see ¶G below). MOSFETs are often used as switches. In this mode of operation a large gate voltage (e.g., 10 V) is applied to make the channel resistance low enough to approximate a closed switch. More on FET switches in sections ¶¶O–Q below.

¶F. Square-law.

Over a large region of gate voltages greater than V_{th} , and for drain voltages above a volt or so (i.e., in the saturated region), a FET’s drain current behaves like a square-law device; that is, its drain current is proportional to the square of the excess gate-drive voltage ($V_{GS}-V_{th}$)², see Figure 3.14 and eq’n 3.2. This is sometimes called the *quadratic* region. The threshold voltage V_{th} is generally determined with an extrapolated $\sqrt{I_D}$ plot, as the figure shows. For V_{GS} below threshold the FET is in the subthreshold region; see ¶I below.

¶G. Transconductance and Amplifiers.

Transconductance g_m is the change in output drain current caused by a change in gate voltage: $g_m=i_D/v_{GS}$ (the lower-case *i* and *v* signify small signals). Common-source FET amplifiers (§3.2.3, Figures 3.28 and 3.29) have voltage gain $G=-g_m R_D$, where R_D is the drain load resistance. In contrast to BJTs (where $g_m \propto I_C$), the transconductance of FETs rises only as $\sqrt{I_D}$ in the important quadratic region; see Figures 3.53 and 3.54. As a consequence FET amplifiers with resistive drain loads have lower gain when designed to operate at higher current, because R_D is generally chosen inversely proportional to drain current. The FET’s internal output resistance also acts as a load resistance, thus

limiting gain (“ G_{\max} ”) even with an ideal current-source drain load; see §3.3.2 eq’n 3.13, and Table 3.1.

When used as a *follower*, an FET has an output impedance $r_{\text{out}}=1/g_m$, see ¶K below.

¶H. Biasing JFET Amplifiers.

JFETs are well suited for making signal amplifiers (by contrast there are few viable small discrete MOSFETs), and they work especially well in low-noise amplifiers. But there’s one very painful issue analog designers face: the uncertain value of the gate operating voltage for any given part. Scanning the min and max columns for $V_{GS(\text{off})}$ in the JFET Table 3.1 on page 141, we see values for a particular JFET that range from -1 V to -7 V , or -0.4 V to -4 V . The latter is a 10:1 ratio! Figure 3.17 shows V_{GS} histograms for 300 parts, 100 each for three different JFET types in a family. Here we see gate voltage spreads of about 1 V, which you might rely upon if you buy a batch of parts from one manufacturer and measure them. But, *caution*: Figures 3.51 and 3.52 show how the same part type may vary when purchased from different manufacturers. To deal with the uncertainty, special biasing schemes are often required in FET amplifier circuits. Figures 3.25 and 3.41 show examples of the load-line concept for analyzing amplifier biasing.

¶I. Subthreshold Region.

The simple FET formula of eq’n 3.2 predicts zero drain current when the gate voltage reaches threshold ($V_{GS}=V_{\text{th}}$). In reality the drain current is not zero, and transitions smoothly to a subthreshold region (see Figure 3.16) where the FET looks more like a BJT, with its exponential Ebers-Moll characteristic (§2.3.1). In this region (where I_D rises exponentially with V_{GS}) we’re glad to see a higher $g_m \propto I_D$; but sadly the FET proportionality constant is usually 2× to 5× smaller than for BJTs, see Figure 3.53.

¶J. Self-biased Amplifiers.

Depletion-mode MOSFETs (and all JFETs) operate with a reverse voltage on their gates, which allows them to be self-biased (§3.2.6A). The source terminal is “higher” than the gate terminal, so a source resistor connected between them sets the drain current to $I_D=V_{GS}/R$. This is also a convenient way to make a 2-terminal current source, but the tolerance will be poor due to the wide variability in V_{GS} , see ¶H. Alternately the V_{GS} voltage available at the source pin may be used to operate a current-setting IC like the LM334.

¶K. Source Followers.

Source followers (§3.2.6), Figure 3.40 have a nominal gain of 1, analogous to the BJT emitter follower. Because of their lower g_m , however, they have considerably higher output resistance, $r_{\text{out}}=1/g_m$, so the ideal unity gain is reduced by load resistance, see eq’n 3.7.

¶L. FETs as Variable Resistors.

At low drain voltages ($V_{DS} \ll V_{GS}$) FETs act as variable resistors programmed by the gate voltage. Because the slope varies with V_{DS} , however, the resistance is somewhat nonlinear. But there’s a simple trick to linearize this resistance, by exploiting the quadratic behavior of FETs, see Figures 3.46 and 3.47.

¶M. FET Gate Current.

The gate of a JFET forms a diode junction with the channel; it’s normally reverse-biased, with some non-zero dc leakage current (§3.2.8). This current roughly doubles for every 10°C temperature increase; furthermore it increases dramatically at high drain currents and drain voltages due to impact ionization, see Figure 3.49. MOSFET gates do not suffer from either of these leakage-current-increasing effects. In contrast to the generally negligible dc gate leakage, the input capacitance C_{iss} of FETs (which can be quite high, many hundreds of pF for large power MOSFETs) often presents a substantial ac load. Use a gate-driver chip (Table 3.8) to provide the high transient currents needed for rapid switching.

¶N. JFET Switches.

JFETs can be used as analog-signal switches, as in the *n*-channel switch of Figure 3.62. The switch is OFF when the gate is taken at least V_{th} below than the most negative input signal. To turn the switch ON the gate voltage must be allowed to equal the source. JFETs are symmetrical, so e.g., for an *n*-channel part, the “source” would be the most negative pin. Large-die JFETs work well as power switches up to 100 mA; Table 3.1 lists parts with R_{ON} as low as 3Ω .

¶O. CMOS Switches.

CMOS signal switches are made with a parallel pair of complementary *n*- and *p*-channel MOSFETs. This reduces R_{ON} as shown in Figure 3.61, and beneficially causes cancellation of most of the injected charge transfer (§3.4.2E), see Figure 3.79. The injected charge scales roughly inversely proportional to R_{ON} (Figure 3.81), so there’s a tradeoff between desirably low on-resistance and desirably low self-capacitance. As an example, Table 3.3 lists a switch with an impressive $R_{\text{ON}}=0.3\Omega$ – but it’s burdened

with a whopping 300 pF of self-capacitance. A T-switch configuration can be used to reduce the signal feedthrough at high-frequencies, see Figure 3.77.

¶P. CMOS Logic Gates.

See Figure 3.90. A series pair of complementary (*n*- and *p*-channel) small-geometry MOSFETs between the positive rail and ground forms the simplest logic inverter (Figure 3.90); more switches can be arranged to make CMOS logic gates (e.g., Figure 3.91, §3.4.4), with the attractive property of nearly zero static power, except when switching. CMOS logic is covered extensively in Chapters 10 and 12, and is the basis for all contemporary digital processors.

¶Q. MOSFET Power Switches.

Most power MOSFETs (§3.5) are enhancement type, available in both *n*- and *p*-channel polarities. They are very popular for use as high-current high-voltage power switches. A few relevant parameters are the breakdown voltage V_{DSS} (ranging from 20 V to 1.5 kV for *n*-channel, and to 500 V for *p*-channel); the channel on-resistance $R_{DS(ON)}$ (as low as 2 mΩ); the power-handling ability (as high as 1000 W with the case held unrealistically at 25°C); and the gate capacitance C_{iss} (as high as 10,000 pF), which must be charged and discharged during MOSFET switching, see ¶S below. Table 3.4a lists representative small-package *n*-channel parts rated to +250 V and *p*-channel parts of all sizes to -100 V; Table 3.4b extends the *n*-channel selection to higher voltage and current; more complete tables are found in Chapter 3x.

¶R. Maximum Current.

MOSFET datasheets list a maximum continuous rated current, specified however at an unrealistic 25°C case temperature. This is calculated from $I_{D(max)}^2 R_{DS(ON)} = P_{max}$, substituting a maximum power $P_{max} R_{OJC} = \Delta T_{JC} = 150^\circ\text{C}$ (see §9.4), where they have assumed $T_{J(max)} = 175^\circ\text{C}$ (thus a 150°C ΔT_{JC}), and they use the value of $R_{DS(ON)}$ (max) at 175°C from an R_{DS} tempco plot (e.g., see Figure 3.116). That is, $I_{D(max)} = \sqrt{\Delta T_{JC} / R_{OJC} R_{ON}}$. Some datasheets show the calculation for a more realistic 75°C or 100°C case temperature. Even so, you don't really want to run your MOSFET junction at 175°C, so we recommend using a lower maximum continuous I_D and corresponding P_{diss} .

¶S. Gate Charge.

The capacitances in power MOSFETs that slow down switching are most easily analyzed with gate-charge plots, like Figure 3.101. First consider turn-ON: as current flows

into the gate capacitance $C_{iss} + C_{rss}$ (dominated by C_{iss}) the gate voltage rises. There is a switching delay, because the FET's drain remains off until the gate voltage is high enough for the FET to sink the drain current. Then the drain voltage starts to fall, as seen in Figures 3.102 and 3.103. The falling drain creates a reverse gate current $I = C_{rss} dV_D/dt$ that prevents further increase in the gate voltage. Put another way, the falling slew-rate $dV_D/dt = I_G/C_{rss}$ is set by the gate current available to charge the feedback (Miller) capacitance C_{rss} . When V_{DS} reaches zero the gate resumes charging, now at a slower rate because the C_{rss} contribution to total gate capacitance is larger at $V_{DS}=0$, see Figure 3.100). The MOSFET does not reach its intended low value of $R_{DS(ON)}$ until the gate attains its full drive voltage. Turn-off proceeds similarly. MOSFET datasheets include values for C_{iss} and C_{rss} , but the latter is typically at $V_{DS}=25$ V, so you need to go to the datasheet plots of capacitances versus drain voltage.

¶T. MOSFET Gate Damage.

MOSFET gates typically have ± 20 V to ± 30 V maximum ratings, beyond which the very thin metal-oxide gate-channel insulator can be permanently damaged, see Figure 3.105. Be sure to discharge static charge before installation of discrete MOSFETs and MOS ICs.

¶U. FET versus BJT for Power Switching.

See §3.5.4H; see also ¶Z below.

¶V. MOSFET Switch Polarity.

Both *n*- and *p*-channel polarities of MOSFETs can be used to switch a voltage, see Figure 3.106 where most of the circuits show a conventional approach with a *p*-channel FET switching a positive voltage. But circuit E shows an *n*-channel FET doing the same task, with an additional voltage source powering the gate (the better-performing *n*-channel FET is preferred if it can be easily used, see §3.1.2). Figure 3.107 illustrates the use of photodiodes to power the high-side gates, to make "floating" switches.

¶W. Power MOSFET Amplifiers.

Unlike bipolar power transistors, power MOSFETs have a wide safe-operating area (SOA) and do not suffer from second breakdown (see Figure 3.95), which is due to a localized thermal-runaway heating problem. Figure 3.119 shows typical class-AB biasing techniques necessary for use in linear power amplifiers.

¶X. Depletion-mode Power MOSFETs.

Although most power MOSFETs are enhancement-mode types, *n*-channel depletion-mode types are available; §3.5.6D shows some applications. See also Table 3.6 on page 210.

¶Y. Paralleling Power MOSFETs.

When used as switches, yes, but when used in power amplifiers, no, at least not without high-value source-ballast resistors! Figure 3.117B shows an elegant active-feedback

workaround for use with regulator pass elements.

¶Z. IGBTs.

IGBTs are an alternative to power MOSFETs, see §3.5.7 where we show a comparison between power MOSFETs, IGBTs and BJTs. They're primarily useful at voltages above 300 V and switching rates below 100 kHz, though there are some nice IGBTs for use at RF, for example the IRGB4045, good for 150 W or more at 20 MHz.

OPERATIONAL AMPLIFIERS

CHAPTER 4

4.1 Introduction to op-amps – the “perfect component”

In the previous three chapters we learned about circuit design with “discrete components,” both active and passive. Our basic building blocks were transistors, both bipolar (BJT) and field-effect (FET), along with the resistors, capacitors, and other components that are needed to set bias, couple and block signals, create load impedances, and so on.

With those tools we have gone quite far. We’ve learned how to design simple power supplies, signal amplifiers and followers, current sources, dc and differential amplifiers, analog switches, power drivers and regulators, and even some rudimentary digital logic.

But we’ve also learned to struggle with imperfections. Voltage amplifiers suffer from nonlinearity (a grounded-emitter amplifier with a 1 mV input signal has $\sim 1\%$ distortion), which you can trade off against voltage gain (by adding emitter degeneration); differential amplifiers have input unbalance, typically tens of millivolts (with bipolar transistors), ten times more with discrete junction-FETs (JFETs); in bipolar design you have to worry about input current (often substantial), and the ever-present V_{BE} and its variation with temperature; in FET design you trade absence of input current for unpredictability of V_{GS} ; and so on.

We’ve seen hints that things can be better, in particular the remarkable linearizing effects of negative feedback (§2.5.3), and its ability to make overall *circuit* performance less dependent on *component* imperfections. It is negative feedback that gives the emitter-degenerated amplifier its linearity advantage over the grounded-emitter amplifier (at the cost of voltage gain). And in the high-loop-gain limit, negative feedback promises circuit performance largely independent of transistor imperfections.

Promised, but not yet delivered: the high-gain amplifier blocks we need to get high loop gain in a feedback arrangement still involve substantial design efforts – the hallmark of complex circuits implemented with discrete (as opposed to integrated) components.

With this chapter we enter the promised land! The op-amp is, essentially, a “perfect part”: a complete integrated amplifier gain block, best thought of as a dc-coupled differential amplifier with single-ended output, and with extraordinarily high gain. It also excels in precise input symmetry and nearly zero input current. Op-amps are designed as “gain engines” for negative feedback, with such high gain that the circuit performance is set almost entirely by the feedback circuitry. Op-amps are small and inexpensive, and they should be the starting point for nearly every analog circuit you design. In most op-amp circuit designs we’re in the regime where they are essentially perfect: with them we will learn to build nearly perfect amplifiers, current sources, integrators, filters, regulators, current-to-voltage converters, and a host of other modules.

Op-amps are our first example of *integrated circuits* – many individual circuit elements, such as transistors and resistors, fabricated and interconnected on a single “chip” of silicon.¹ Figure 4.1 shows some IC op-amp packaging schemes.

4.1.1 Feedback and op-amps

We first met negative feedback in Chapter 2, where we saw that the process of coupling the output back, in such a way as to cancel some of the input signal, improved characteristics such as linearity, flatness of response, and predictability. As we saw quantitatively, the more negative feedback that is used, the less the resultant amplifier characteristics depend on the characteristics of the open-loop (no-feedback) amplifier, ultimately depending only on the properties of the feedback network itself. Operational amplifiers are typically used in this *high-loop-gain* limit, with *open-loop* voltage gain (no feedback) of a million or so.

A feedback network can be frequency-dependent, to produce an equalization amplifier (for example the

¹ The first operational amplifiers were made with vacuum tubes, followed by implementations with discrete transistors. See §4x.1 for a description (with photo and schematics) of a once-popular vacuum-tube op-amp, the Philbrick K2-W.

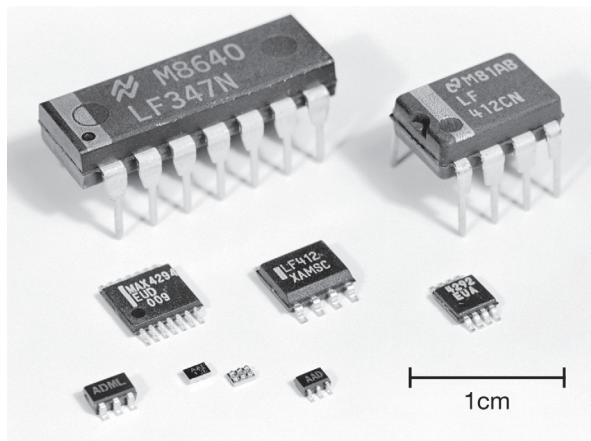


Figure 4.1. Op-amps (and other linear ICs) come in a bewildering variety of “packages,” most of which are represented in this photograph. Top row, left to right: 14-pin plastic dual in-line package (DIP), 8-pin plastic DIP (“mini-DIP”). Middle row: 14-pin thin-shrink small-outline package (TSSOP), 8-pin small-outline package (SO-8), 8-pin TSSOP (“ μ MAX”). Bottom row: 5-pin small-outline transistor package (SOT23), 6-ball chip-scale package (CSP – top and bottom views), 5-pin SC-70. The 14-pin packages hold quad op-amps (i.e., four independent op-amps), the 8-pin packages hold duals, and the rest are singles. (TSSOP and smaller packages courtesy of Travis Eichhorn, Maxim Semiconductor.)

treble and bass “tone control” stage of amplification that you find in most audio systems); or it can be amplitude-dependent, producing a nonlinear amplifier (a popular example is a logarithmic amplifier, built with feedback that exploits the logarithmic V_{BE} versus I_C of a diode or transistor). It can be arranged to produce a current source (near-infinite output impedance) or a voltage source (near-zero output impedance), and it can be connected to generate very high or very low input impedance. Speaking in general terms, the property that is sampled to produce feedback is the property that is improved. Thus, if you feed back a signal proportional to the output current, you will generate a good current source.

As we remarked in §2.5.1, feedback can be arranged intentionally to be *positive*, for example to make an oscillator, or, as we’ll see later, to make a Schmitt trigger circuit. That’s the *good* kind of positive feedback. The bad kind occurs, uninvited (and unwelcome), when a negative-feedback circuit is burdened with sufficient accumulated phase shifts at some frequency to produce overall positive feedback, and oscillations. This can occur for a variety of reasons. We’ll discuss this important subject, and see how to prevent unwanted oscillations by *frequency compensation*, the topic of §4.9 at the end of the chapter.

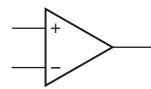


Figure 4.2. Op-amp symbol.

Having made these general comments, we now look at a few feedback examples with op-amps.

4.1.2 Operational amplifiers

The operational amplifier is a very high-gain dc-coupled differential amplifier with a single-ended output. You can think of the classic long-tailed pair (§2.3.8) with its two inputs and single output as a prototype, although real op-amps have much higher gain (typically 10^5 to 10^6) and lower output impedance, and they allow the output to swing through most or all of the supply range (you often use a split supply, for example ± 5 V). Operational amplifiers are available in literally thousands of types, with the universal symbol shown in Figure 4.2, where the (+) and (−) inputs do as expected: the output goes positive when the noninverting input (+) goes more positive than the inverting input (−), and vice versa. The (+) and (−) symbols don’t mean that you have to keep one positive with respect to the other, or anything like that; they just tell you the relative phase of the output (which is important to keep negative feedback *negative*). Using the words “noninverting” and “inverting,” rather than “plus” and “minus” helps avoid confusion. Power-supply connections are frequently not displayed, and there is no ground terminal. Operational amplifiers have enormous voltage gain, and they are *never* (well, hardly ever) used without feedback. Think of an op-amp as fodder for feedback. The open-loop gain is so high that, for any reasonable closed-loop gain, the characteristics depend on only the feedback network. Of course, at some level of scrutiny this generalization must fail. We will start with a naïve view of op-amp behavior and fill in some of the finer points later, when we need to.

There are literally thousands of different op-amps available, offering various performance tradeoffs that we will explain later (look ahead to Tables 4.2a,b, 5.5, or 8.3 if you want to see a small sample of what’s available). A very good all-around performer is the popular LF411 (“411” for short), originally introduced by National Semiconductor. Like many op-amps, it is a wee beastie packaged in the so-called mini-DIP (dual in-line package) or SOIC (small-outline IC), and it looks as shown in Figure 4.3. It is inexpensive (less than \$1) and easy to use; it comes in an improved grade (LF411A) and also in a version containing

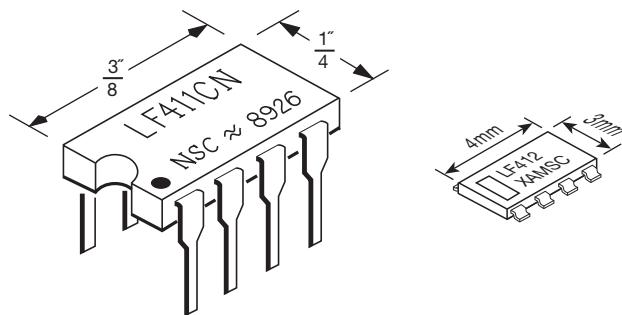


Figure 4.3. Mini-DIP and SOIC packages.

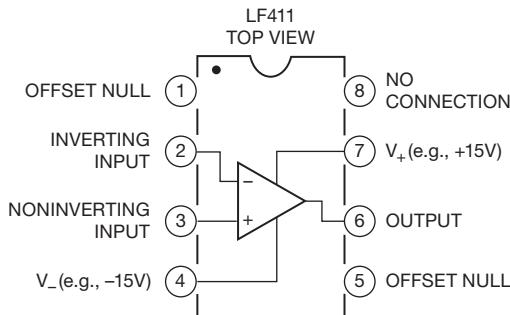


Figure 4.4. Pin connections for LF411 op-amp in 8-pin DIP.

two independent op-amps (LF412, called a “dual” op-amp). We will adopt the LF411/LF412 throughout this chapter as our “standard” op-amp, and we recommend it (or perhaps the versatile LMC6482) as a good starting point for your circuit designs.

Inside the 411 is a piece of silicon containing 24 transistors (21 BJTs, 3 FETs), 11 resistors, and 1 capacitor. (You can look ahead to Figure 4.43 on page 243 to see a simplified circuit diagram of its innards.) The pin connections are shown in Figure 4.4. The dot in the upper-left-hand corner, or notch at the end of the package, identifies the end from which to begin counting the pin numbers. As with most electronic packages, you count pins counterclockwise, viewing from the top. The “offset null” terminals (also known as “balance” or “trim”) have to do with correcting (externally) the small asymmetries that are unavoidable when making the op-amp. More about this later in the chapter.

4.1.3 The golden rules

Here are the simple rules for working out op-amp behavior with external negative feedback. They’re good enough for almost everything you’ll ever do.

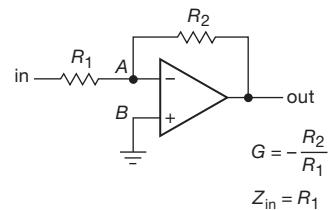


Figure 4.5. Inverting amplifier.

First, the op-amp voltage gain is so high that a fraction of a millivolt between the input terminals will swing the output over its full range, so we ignore that small voltage and state golden rule I.

- I.** The output attempts to do whatever is necessary to make the voltage difference between the inputs zero.

Second, op-amps draw very little input current (about 50 pA for the inexpensive JFET-input LF411, and often less than a picoamp for MOSFET-input types); we round this off, stating golden rule II.

- II.** The inputs draw no current.

One important note of explanation: golden rule I doesn’t mean that the op-amp actually changes the voltage at its *inputs*. It can’t do that. (How could it, and be consistent with golden rule II?) What it does is “look” at its input terminals and swing its output terminal around so that the external feedback-network brings the input differential to zero (if possible).

These two rules get you quite far. We illustrate with some basic and important op-amp circuits, and these will prompt a few cautions listed in §4.2.7.

4.2 Basic op-amp circuits

4.2.1 Inverting amplifier

Let’s begin with the circuit shown in Figure 4.5. The analysis is simple, if you remember your golden rules.

1. Point B is at ground, so rule I implies that point A is also.
2. This means that (a) the voltage across R_2 is V_{out} and (b) the voltage across R_1 is V_{in} .
3. So, using rule II, we have $V_{\text{out}}/R_2 = -V_{\text{in}}/R_1$.

In other words, the voltage gain ($G_V \equiv V_{\text{out}}/V_{\text{in}}$) is

$$G_V = -R_2/R_1 \quad (4.1)$$

Later you will see that it’s sometimes better not to ground B directly, but through a resistor – but don’t worry about that now.

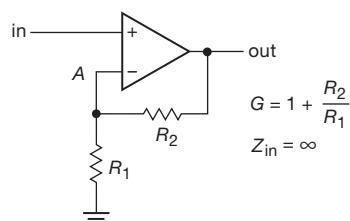


Figure 4.6. Noninverting amplifier.

Our analysis seems almost too easy! In some ways it obscures what is actually happening. To understand how feedback works, just imagine some input level, say +1 volt. For concreteness, imagine that R_1 is 10k and R_2 is 100k. Now, suppose the output decides to be uncooperative, and sits at zero volts. What happens? R_1 and R_2 form a voltage divider, holding the inverting input at +0.91 volts. The op-amp sees an enormous input unbalance, forcing the output to go negative. This action continues until the output is at the required -10.0 volts, at which point both op-amp inputs are at the same voltage, namely ground. Similarly, any tendency for the output to go more negative than -10.0 volts will pull the inverting input below ground, forcing the output voltage to rise.

What is the input impedance? Simple. Point A is always at zero volts (it's called a *virtual ground*). So $Z_{in} = R_1$. At this point you don't yet know how to figure the output impedance; for this circuit, it's a fraction of an ohm.

Note that this analysis is true even for dc – it's a dc amplifier. So if you have a signal source that has a dc offset from ground (collector of a previous stage, for instance), you may want to use a coupling capacitor (sometimes called a blocking capacitor, since it blocks dc but couples the signal). For reasons you will see later (having to do with departures of op-amp behavior from the ideal), it is usually a good idea to use a blocking capacitor if you're interested only in ac signals anyway.

This circuit is known as an *inverting amplifier*. Its one undesirable feature is the low input impedance, particularly for amplifiers with large (closed-loop) voltage gain, where R_1 tends to be rather small. That is remedied in the next circuit (Figure 4.6).

4.2.2 Noninverting amplifier

Consider Figure 4.6. Again, the analysis is simplicity itself:

$$V_A = V_{in}.$$

But V_A comes from a voltage divider: $V_A = V_{out}R_1/(R_1 + R_2)$. Set $V_A = V_{in}$, and you get a voltage gain of

$$G_V = 1 + R_2/R_1. \quad (4.2)$$

This is a *noninverting amplifier*. In the approximation we are using, the input impedance is infinite (with the JFET-input 411 it would be $10^{12}\Omega$ or more; a BJT-input op-amp will typically exceed $10^8\Omega$). The output impedance is still a fraction of an ohm. As with the inverting amplifier, a detailed look at the voltages at the inputs will convince you that it works as advertised.

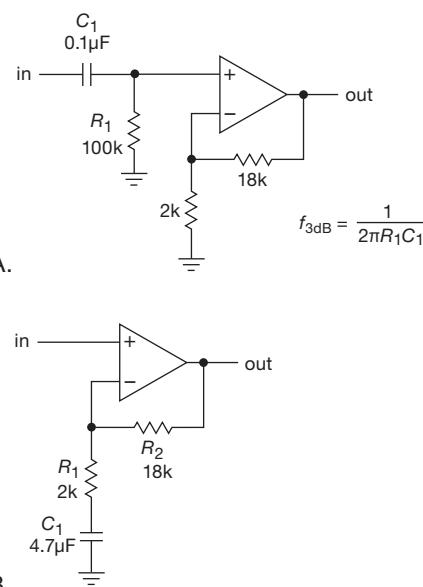


Figure 4.7. Amplifiers for ac signals: A. ac-coupled noninverting amplifier, B. blocking capacitor rolls off the gain to unity at dc.

A. An ac amplifier

The basic noninverting amplifier, like the inverting amplifier earlier, is a dc amplifier. If the signal source is ac-coupled, you must provide a return to ground for the (very small) input current, as in Figure 4.7A. The component values shown give a voltage gain of 10 and a low-frequency 3 dB point of 16 Hz.

If only ac signals are being amplified, it is often a good idea to “roll off” the gain to unity at dc, especially if the amplifier has large voltage gain, to reduce the effects of finite “input offset voltage” (§4.4.1A). The circuit in Figure 4.7B has a low-frequency 3 dB point of 17 Hz, the frequency at which the impedance of the capacitor C_1 equals R_1 , or 2.0k. Note the large capacitor value required. For noninverting amplifiers with high gain, the capacitor in this ac amplifier configuration may be undesirably large. In that

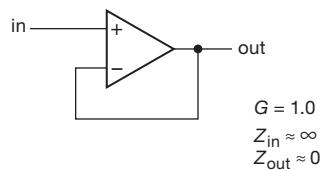


Figure 4.8. Op-amp follower.

case it may be preferable to omit the capacitor and trim the offset voltage to zero, as we will discuss later. An alternative is to raise R_1 and R_2 , perhaps using a T network for the latter (Figure 4.66 on page 259).

In spite of its desirable high input impedance, the non-inverting amplifier configuration is not necessarily to be preferred over the inverting amplifier configuration in all circumstances. As we will see later, the inverting amplifier puts less demand on the op-amp, and therefore gives somewhat better performance. In addition, its virtual ground provides a handy way to combine several signals without interaction. Finally, if the circuit in question is driven from the (stiff) output of another op-amp, it makes no difference whether the input impedance is 10k (say) or infinity, because the previous stage has no trouble driving it in either case.

4.2.3 Follower

Figure 4.8 shows the op-amp version of an emitter follower. It is simply a noninverting amplifier with R_1 infinite and R_2 zero (gain = 1). An amplifier of unity gain is sometimes called a *buffer* because of its isolating properties (high input impedance, low output impedance).

4.2.4 Difference amplifier

The circuit in Figure 4.9A is a *difference amplifier* (sometimes called a *differential amplifier*) with gain R_2/R_1 . This circuit requires precise resistor matching to achieve high common-mode rejection ratios (CMRR). You may be lucky and find a batch of 100k 0.01% resistors at an electronics flea market or surplus outlet; otherwise you can buy precision resistor arrays, with close matching of ratios and temperature coefficients.² All your difference amplifiers

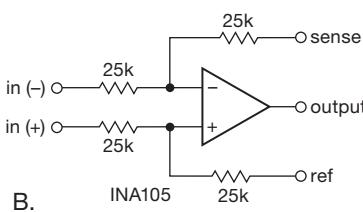
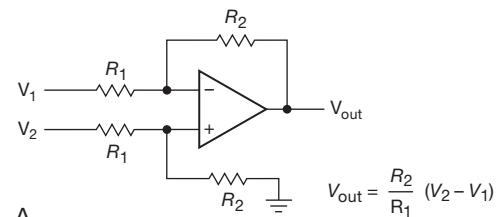


Figure 4.9. Classic difference amplifier: A. Op-amp with matched resistor ratios. B. Integrated version, with uncommitted “sense” and “reference” pins. In the best grade (INA105A) the resistor ratio is matched to better than 0.01%, with a temperature coefficient better than 5 ppm/ $^{\circ}\text{C}$.

will have unity gain, but that's easily remedied with further (single-ended) stages of gain. If you can't find good resistors (or even if you can!), you should know that you can buy this circuit as a convenient packaged difference amplifier, with well-matched resistors; examples are the INA105 or AMP03 ($G = 1$), INA106 ($G=10$ or 0.1), and INA117 or AD629 ($G = 1$ with input dividers; input signals to ± 200 V) from TI/Burr-Brown and Analog Devices (many more are listed in Table 5.7 on page 353). The unity-gain INA105 configuration is shown in Figure 4.9B, with its uncommitted “sense” and “reference” pins. You get the classic difference amplifier by connecting *sense* to the output and *ref* to ground. But the additional flexibility lets you make all sorts of nifty circuits, such as a precision unity-gain inverter, noninverting gain-of-2 amplifier, and noninverting gain-of-0.5 amplifier. We treat difference amplifiers in greater detail in §5.14.

Exercise 4.1. Show how to make these three circuits with an INA105.

There are, in addition, more sophisticated differential amplifier configurations, known officially as “instrumentation amplifiers”; they are discussed in detail in §§5.15 and 5.16, along with a listing in Table 5.8 on page 363.

² For example, the BI Technologies type 664 thin-film quad (four resistors of the same value) in an 8-lead surface-mount IC package (SOIC); these come in accuracies to 0.1%, ratio tracking to 0.05%, and tracking temperature coefficients to ± 5 ppm/ $^{\circ}\text{C}$. They are inexpensive (about \$2 for the best grade), and available from Mouser Electronics, among others. Companies like Vishay have offerings with astonishingly good per-

formance: their best resistor arrays specify worst-case ratio tracking to 0.001%, and tracking temperature coefficient (tempco) to ± 0.1 ppm/ $^{\circ}\text{C}$.